

MOSFET – N-Channel, POWERTRENCH[®], GreenBridge[™] Series of High-Efficiency Bridge Rectifiers

100 V, 6 A, 110 mΩ

FDMQ8403

General Description

This quad MOSFET solution provides ten-fold improvement in power dissipation over diode bridge.

Features

- Max $r_{DS(on)}$ = 110 mΩ at V_{GS} = 10 V, I_D = 3 A
- Max $r_{DS(on)}$ = 175 mΩ at V_{GS} = 6 V, I_D = 2.4 A
- Substantial Efficiency Benefit in PD Solutions
- This Device is Pb-Free, Halid Free and is RoHS Compliant

Applications

- High-Efficiency Bridge Rectifiers

MOSFET MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

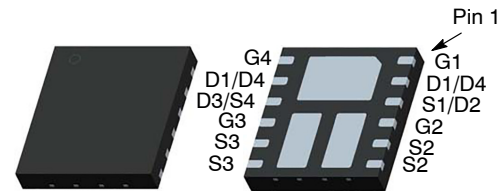
Symbol	Rating	Value	Unit
V_{DS}	Drain to Source Voltage	100	V
V_{GS}	Gate to Source Voltage	±20	V
I_D	Drain Current		A
	– Continuous (Package Limited) T_C = 25°C	6	
	– Continuous (Silicon Limited) T_C = 25°C	9	
	– Continuous (Note 1a.) T_A = 25°C	3.1	
	– Pulsed	12	
P_D	Power Dissipation T_C = 25°C	17	W
	Power Dissipation (Note 1a.) T_A = 25°C	1.9	
T_J, T_{STG}	Operating and Storage Junction Temperature Range	–55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

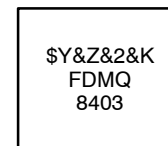
Symbol	Rating	Value	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a.)	65	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1b.)	135	

V_{DSS}	$R_{DS(ON)}$ MAX	I_D MAX
100 V	110 Ω @ 10 V	6 A



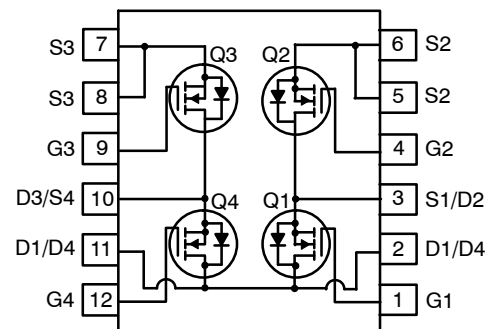
WDFN12 5 x 4.5, 0.8P
(MLP 4.5 x 5)
CASE 511CR

MARKING DIAGRAM



FDMQ8403 = Specific Device Code
\$Y = onsemi Logo
&Z = Assembly plant code
&2 = Date Code format (Year and Week)
&K = Lot Run Traceability Code

PIN CONNECTION



ORDERING INFORMATION

See detailed ordering and shipping information on page 5 of this data sheet.

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
BV_{DSS}	Drain to Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	100	–	–	V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$, Referenced to 25°C	–	72	–	mV/ $^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS} = 0\text{ V}, V_{DS} = 80\text{ V}$	–	–	1	nA
I_{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20\text{ V}, V_{DS} = 0\text{ V}$	–	–	± 100	μA

OFF CHARACTERISTICS

$V_{GS(th)}$	Drain to Source Breakdown Voltage	$V_{GS} = V_{DS}, I_D = 250\text{ }\mu\text{A}$	2	2.8	4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$, Referenced to 25°C	–	–8	–	mV/ $^\circ\text{C}$
$r_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{ V}, I_D = 3\text{ A}$	–	85	110	m Ω
		$V_{GS} = 6\text{ V}, I_D = 2.4\text{ A}$	–	115	175	
		$V_{GS} = 10\text{ V}, I_D = 3\text{ A}, T_J = 125^\circ\text{C}$	–	147	191	
g_{FS}	Forward Transconductance	$V_{DS} = 10\text{ V}, I_D = 3\text{ A}$	–	6	–	S

DYNAMIC CHARACTERISTICS

C_{iss}	Input Capacitance	$V_{DS} = 50\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	–	162	215	pF
C_{oss}	Output Capacitance		–	43	60	pF
C_{rss}	Reverse Transfer Capacitance		–	2.6	5	pF

DYNAMIC CHARACTERISTICS

t _{d(on)}	Turn-On Delay Time	V _{DD} = 50 V, I _D = 3 A, V _{GS} = 10 V, R _{GEN} = 6 Ω		–	4.1	10	ns
t _r	Rise Time			–	1.2	10	ns
t _{d(off)}	Turn-Off Delay Time			–	7.2	15	ns
t _f	Fall Time			–	1.8	10	ns
Q _g	Total Gate Charge	V _{GS} = 0 V to 10 V	V _{DD} = 50 V, I _D = 3 A	–	3	5	nC
Q _g	Total Gate Charge	V _{GS} = 0 V to 5 V		–	1.7	3	nC
Q _{gs}	Gate to Source Charge	V _{DD} = 50 V, I _D = 3 A		–	0.9	–	nC
Q _{gd}	Gate to Drain “Miller” Charge			–	0.8	–	nC

DRAIN-SOURCE DIODE CHARACTERISTICS

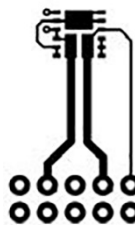
V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = 3\text{ A}$ (Note 2)	–	0.86	1.3	V
t_{rr}	Reverse Recovery Time	$I_F = 3\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$	–	33	53	ns
Q_{rr}	Reverse Recovery Charge		–	23	37	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- $R_{\theta JA}$ is determined with the device mounted on a 1 in^2 pad 2 oz copper pad on a $1.5 \times 1.5\text{ in.}$ board of FR-4 material. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a. 65°C/W when mounted on a 1 in^2 pad of 2 oz copper, the board designed Q1 + Q3 or Q2 + Q4.



b. 135°C/W when mounted on a minimum pad of 2 oz copper, the board designed Q1 + Q3 or Q2 + Q4.

- Pulse Test: Pulse Width $< 300\text{ }\mu\text{s}$, Duty cycle $< 2.0\%$.

TYPICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted.)

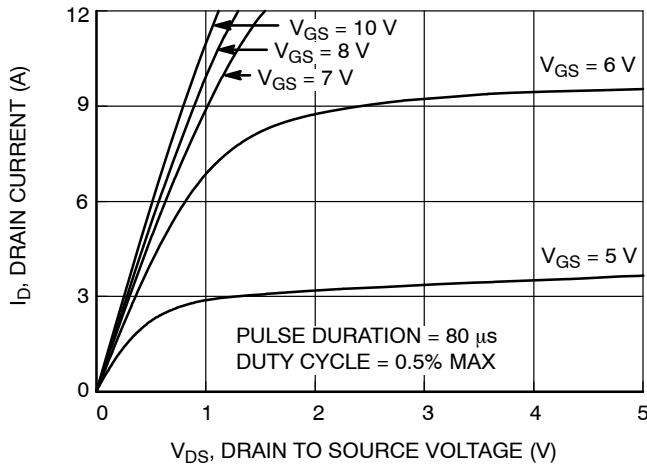


Figure 1. On Region Characteristics

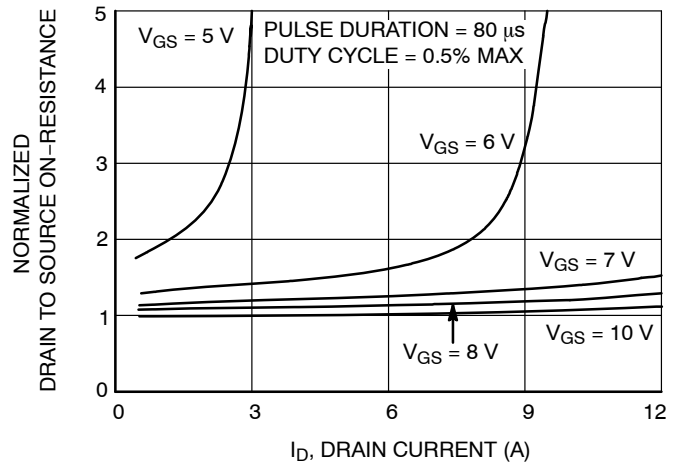


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

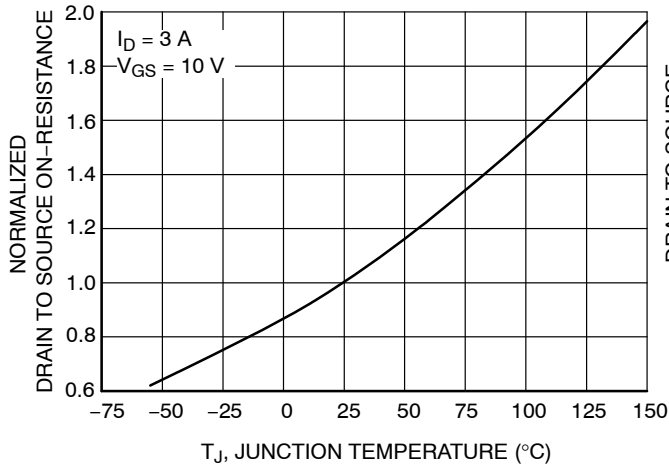


Figure 3. Normalized On Resistance vs. Junction Temperature

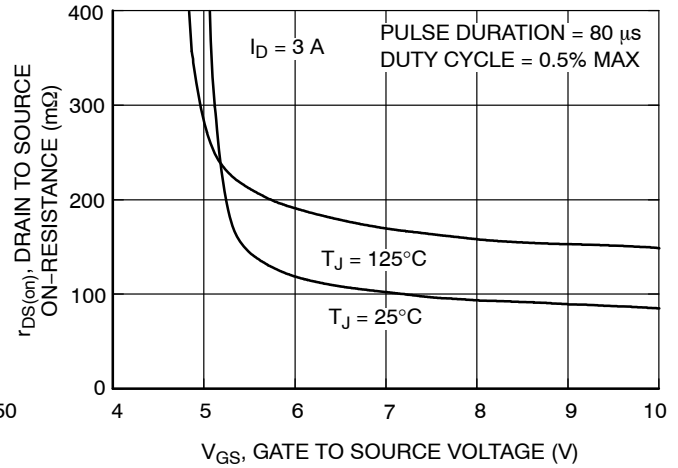


Figure 4. On-Resistance vs. Gate to Source Voltage

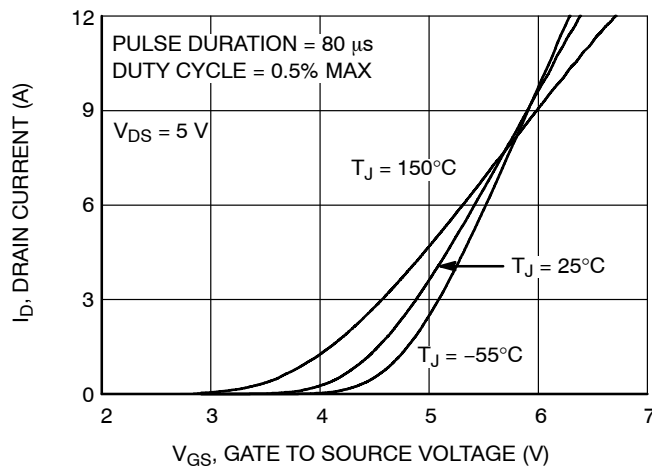


Figure 5. Transfer Characteristics

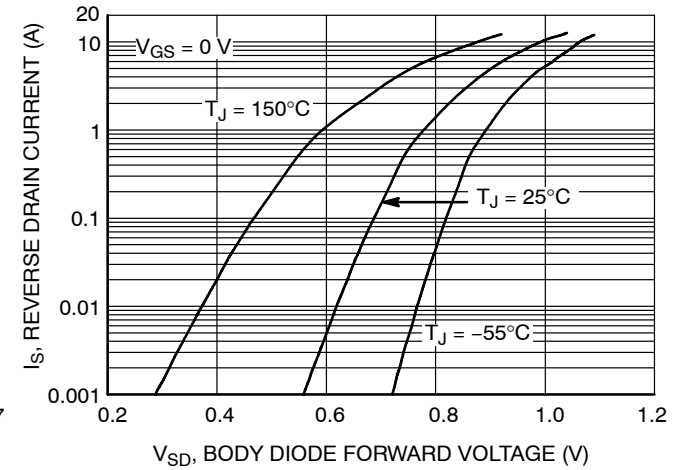


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

TYPICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted) (continued)

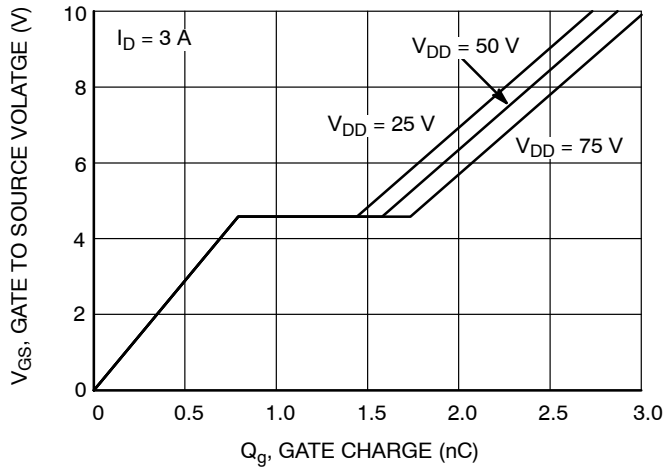


Figure 7. Gate Charge Characteristics

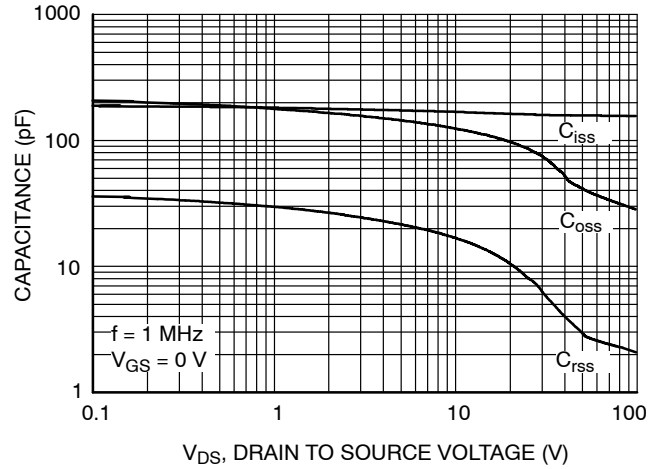


Figure 8. Capacitance vs. Drain to Source Voltage

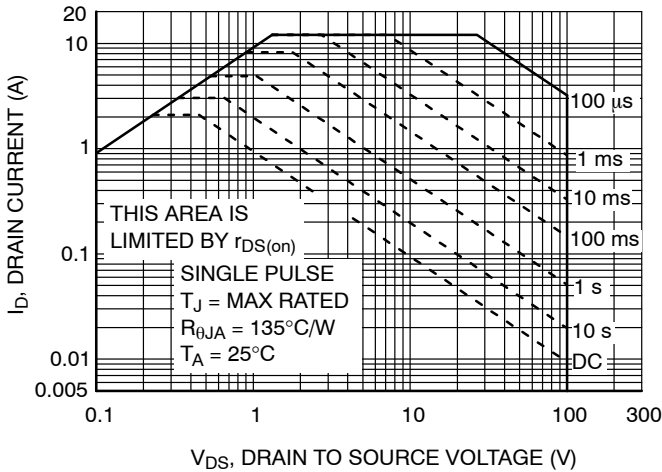


Figure 9. Forward Bias Safe Operating Area

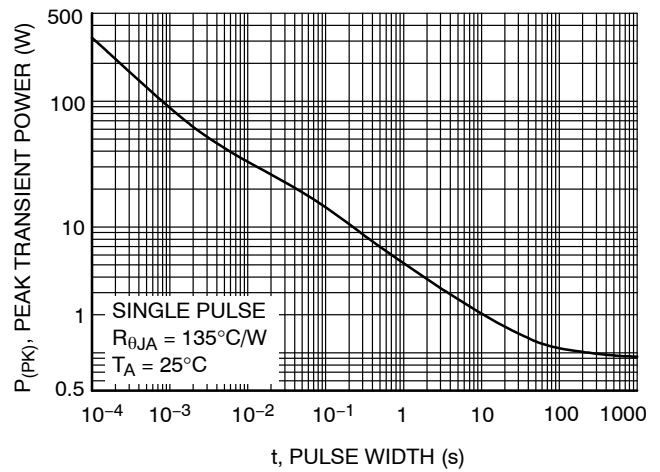


Figure 10. Single Pulse Maximum Power Dissipation

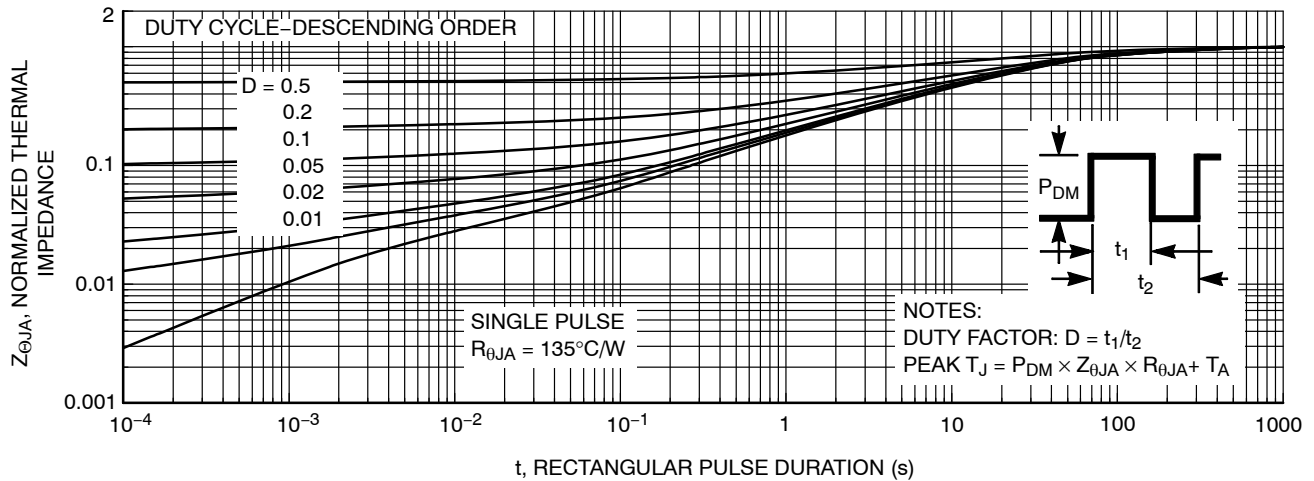


Figure 11. Junction-to-Ambient Transient Thermal Response Curve

FDMQ8403

ORDERING INFORMATION

Device Marking	Device	Package	Reel Size	Tape Width	Shipping [†]
FDMQ8403	FDMQ8403	WDFN12 (Pb-Free)	13"	12 mm	3000 / Tape & Reel

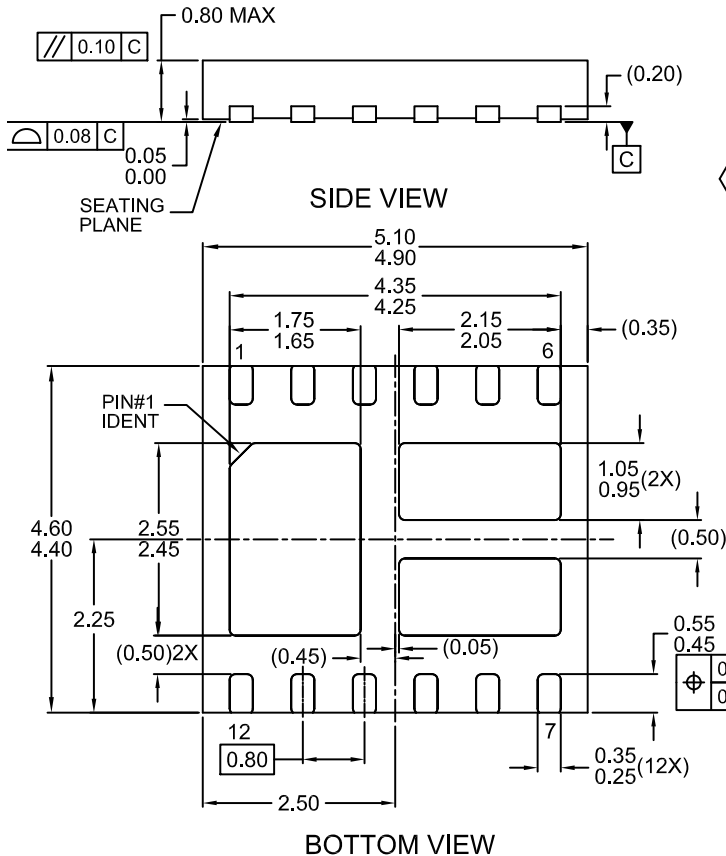
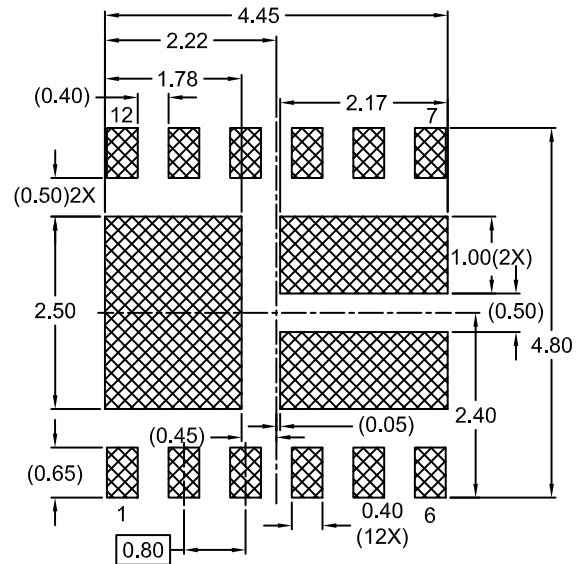
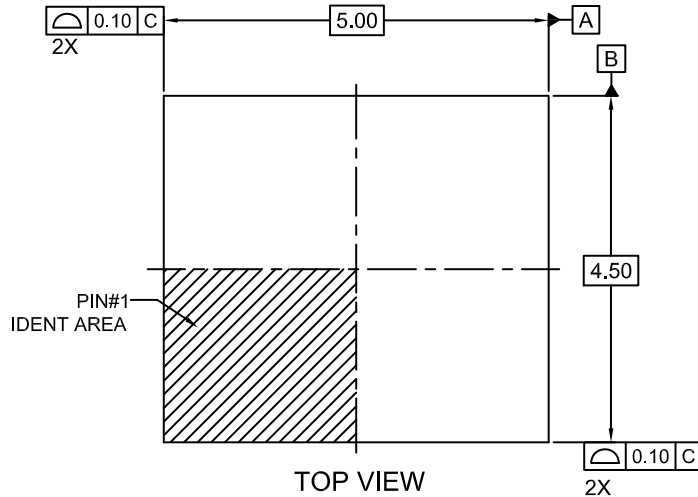
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

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WDFN12 5x4.5, 0.8P
CASE 511CR
ISSUE A

DATE 21 MAR 2017



NOTES:

- A. THIS MKT. DWG. DOES NOT FULLY CONFORM TO JEDEC MO-229 REGISTRATION
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.

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